

Title (en)
DEVICE FOR REMOVING AN INJECTION MOULDED SUBSTRATE FROM AN INJECTION-MOULDING TOOL, AND INJECTION-MOULDING MACHINE EQUIPPED WITH SAME

Title (de)
VORRICHTUNG ZUM ENTNEHMEN EINES SPRITZGEGOSSENEN SUBSTRATES AUS EINEM SPRITZGIESSWERKZEUG

Title (fr)
DISPOSITIF POUR RETIRER UN SUBSTRAT MOULE PAR INJECTION D'UN OUTIL DE MOULAGE PAR INJECTION, ET MACHINE DE MOULAGE PAR INJECTION POURVUE D'UN TEL DISPOSITIF

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Abstract (en)
[origin: WO03037602A1] The invention concerns a device for removing an injection moulded substrate (10) from an injection-moulding tool, comprising a lever (24) capable, by pivoting, of being placed between the halves (2, 4) of the injection-moulding tool or removed from that position, and provided with means for retaining the substrate. In accordance with the invention, for the removal of the cull (11), there is provided outside the tool a substrate-retaining portion (23), which is designed to retain the substrate (10) and includes a recess or an opening (22), said recess or said opening (22) having a shape designed to receive the cull (11). The invention is characterized in that for removal of the cull (11), there is provided inside the tool a guide pin (56) for retaining the substrate (10), which can be inserted into an opening or a recess (55) formed in the substrate (10) after the cull has been separated (11). In those two embodiments, the substrate is form-closed with the retaining part and the pivoting speed of the lever can be increased without any risk of offsetting or releasing the retaining part during the pivoting movement.

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